

FEATURES

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260°C/10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- High surge current capability
- Glass passivated chip junction
- Green compound(halogen&Sb₂O₃ free)

MECHANICAL DATA

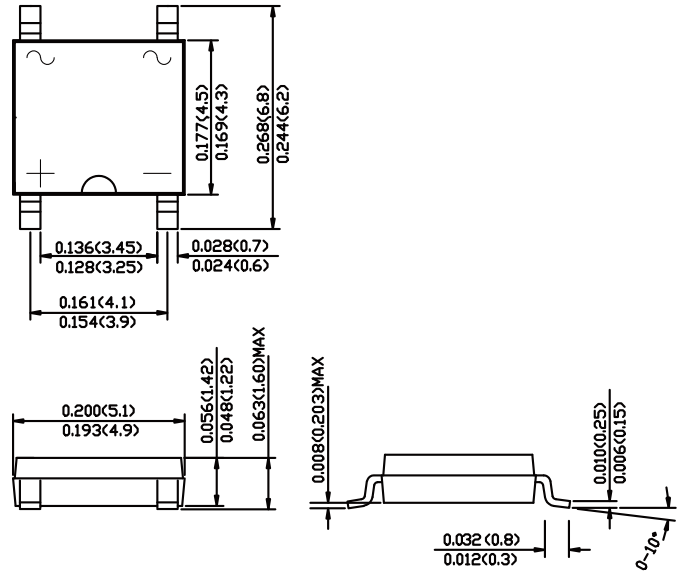
Case: Molded plastic body

Terminals: Plated leads solderable per MIL-STD-750, Method 2026

Polarity: Polarity symbols marked on case

Mounting Position: Any

ABS



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

	SYMBOLS	ABS2	ABS4	ABS6	ABS8	ABS10	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On glass-epoxy P.C.B. On aluminum substrate	I _{F(AV)}			0.8 1.0			A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}			30			A
Maximum instantaneous forward voltage drop per leg at 0.4A	V _F			0.95			V
Maximum DC reverse current at rated DC blocking voltage	I _R			5 100			uA uA
Typical thermal resistance	R _{θJL}			25			°C/W
	R _{θJA}			75			
Operating temperature range	T _J			-55 to +150			°C
storage temperature range	T _{STG}			-55 to +150			°C



FIG.1 FORWARD DERATING CURVE

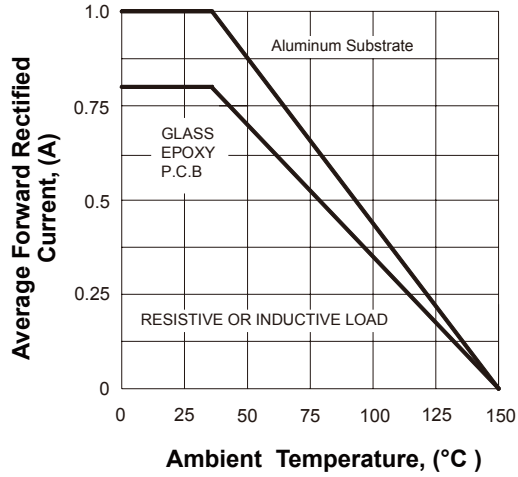


FIG.2 PEAK FORWARD SURGE CURRENT

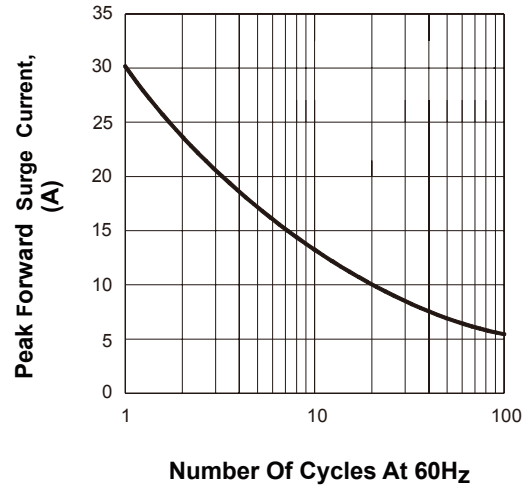


FIG.3 TYPICAL FORWARD CHARACTERISTICS

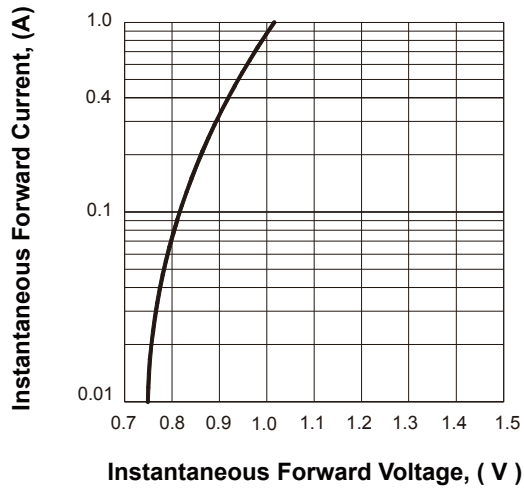


FIG.4 TYPICAL REVERSE CHARACTERISTICS

